

Heat sink for an electronic component especially ceramic circuit board

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A heat sink for an electronic component consists of a composite material based on aluminium or an aluminium alloy containing further material particles or fibers for matching the thermal expansion coefficients or thermal expansion properties of the heat sink and the element to be cooled. An Independent claim is also included for an electronic component consisting of a circuit board adhesively bonded or soldered to the above heat sink. Preferred Features: The further material consists of ceramic (especially silicon carbide), plastic or carbon particles or fibers.

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